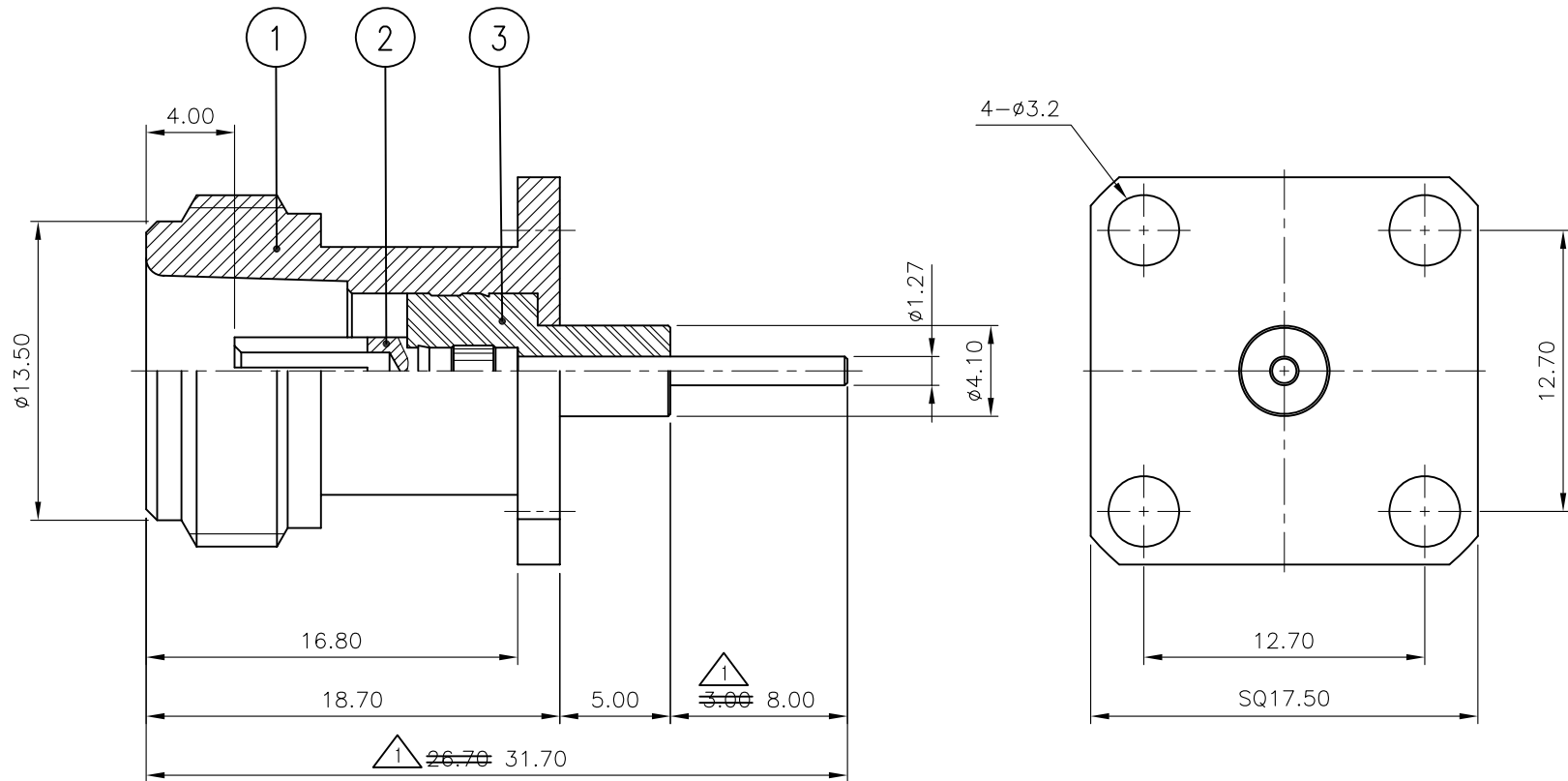


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			2005.12.22.
1	[설번No.연구2006-161] 부적합 개선(PIN 밀링 방지 및 회전 방지 길이 변경)	E.H.KIM	S.J.YOUN	2006.07.18.
2	[설번No.연구2006-164] 기타(PIN 도금 변경)	E.H.KIM	S.J.YOUN	2006.07.20.
3	[설번No.201309-0010] 공용화 (BODY 낙시턱 있는 제품으로 적용,TEF 부물질 현상 관련 코드 변경)	E.H.KIM	I.C.KIM	2013.09.30.



3	INSULATOR	1	TEFLON		DIN02255-N/1 DIN01291-N/1
2	CONTACT	1	BeCu	Silver Plate Gold Plate	DCT02238-5/1
1	BODY	1	MBsBD	Nickel Plate Gold Plate	DBD01510-5/2 DBD00988-5/1 DBD01988-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2013. 09. 30.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		TITLE N50 SOLDER END JS-4H
		DRAWN BY	E.H.KIM	
FINISH		SCALE	UNIT	A4 DWG NO. CN01495-7/1 REVISION 3 SHEET 1 of 1
		3/1	mm	